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## Linear LED Driver, 24-Channel, Bus Controlled

### Overview

The LV5239TA is a serial bus controlled linear low side driver for LEDs (or other loads). The 24 channels are grouped in 3 color blocks (RGB) of 8 channels each. The ON-time for each channel can be programmed by an 8 bit register. The reference current is programmed by a single resistor, a 3 bit register defines the current for each color block as a fraction (20 to 100%) of the reference current to adjust for color temperature.

Systems parameters can be programmed via 2 wire serial bus, or 3 wire SPI bus with EN.

### Features

- LED supply from 3 V to TBDV with transient tolerance up to 42 V.
- System supply from 3 V to 12 V with transient tolerance up to 13.6 V.
- Up to 100 mA resistor defined maximum current for all channels.
- 3 bit individually adjustable current for each color group RGB.
- 8 bit luminance dimming for each channel.
- 2 or 3 wire bus interface with up to 32 slave addresses.
- Thermal and undervoltage lock-out protection.
- Thermally efficient exposed die 48 pin TQFP package for operation up to 85°C ambient.

### Typical Applications

- Gaming (slot machine) and entertainment equipment.
- LED displays.
- Digital information signs.

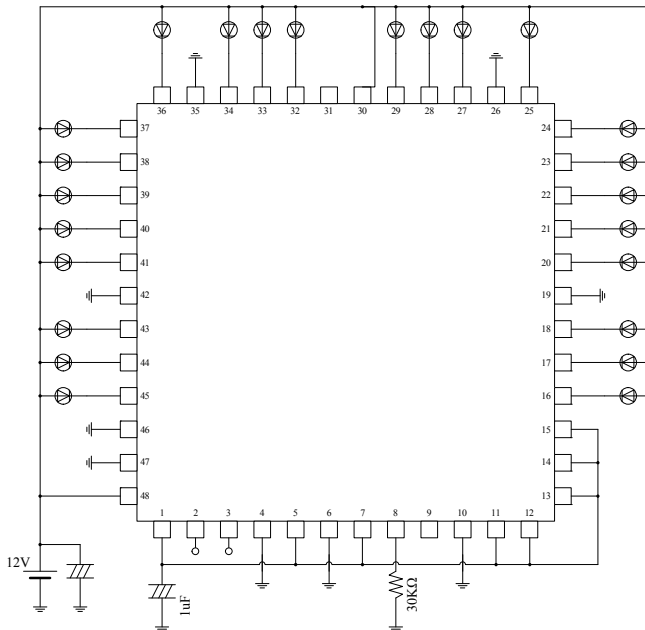
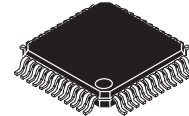


Figure 1: Typical Application Diagram



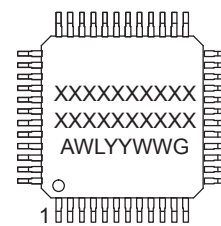
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TQFP48 EP 7x7mm

### GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 YY = Year  
 WW = Work Week  
 G = Pb-Free Package

### ORDERING INFORMATION

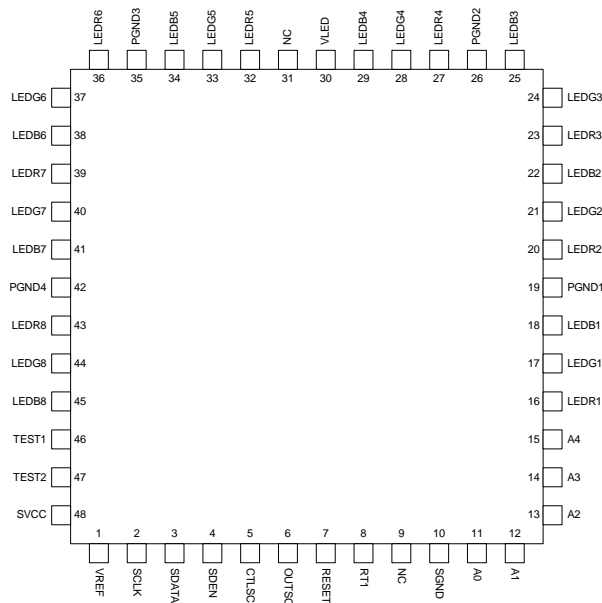
Ordering Code:  
 LV5239TAZ-NH

Package  
 TQFP48 EP  
 (Pb-Free / Halogen Free)

Shipping (Qty / packing)  
 1000 / Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.  
[http://www.onsemi.com/pub\\_link/Collateral/BRD8011-D.PDF](http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF)

## Pin Assignment



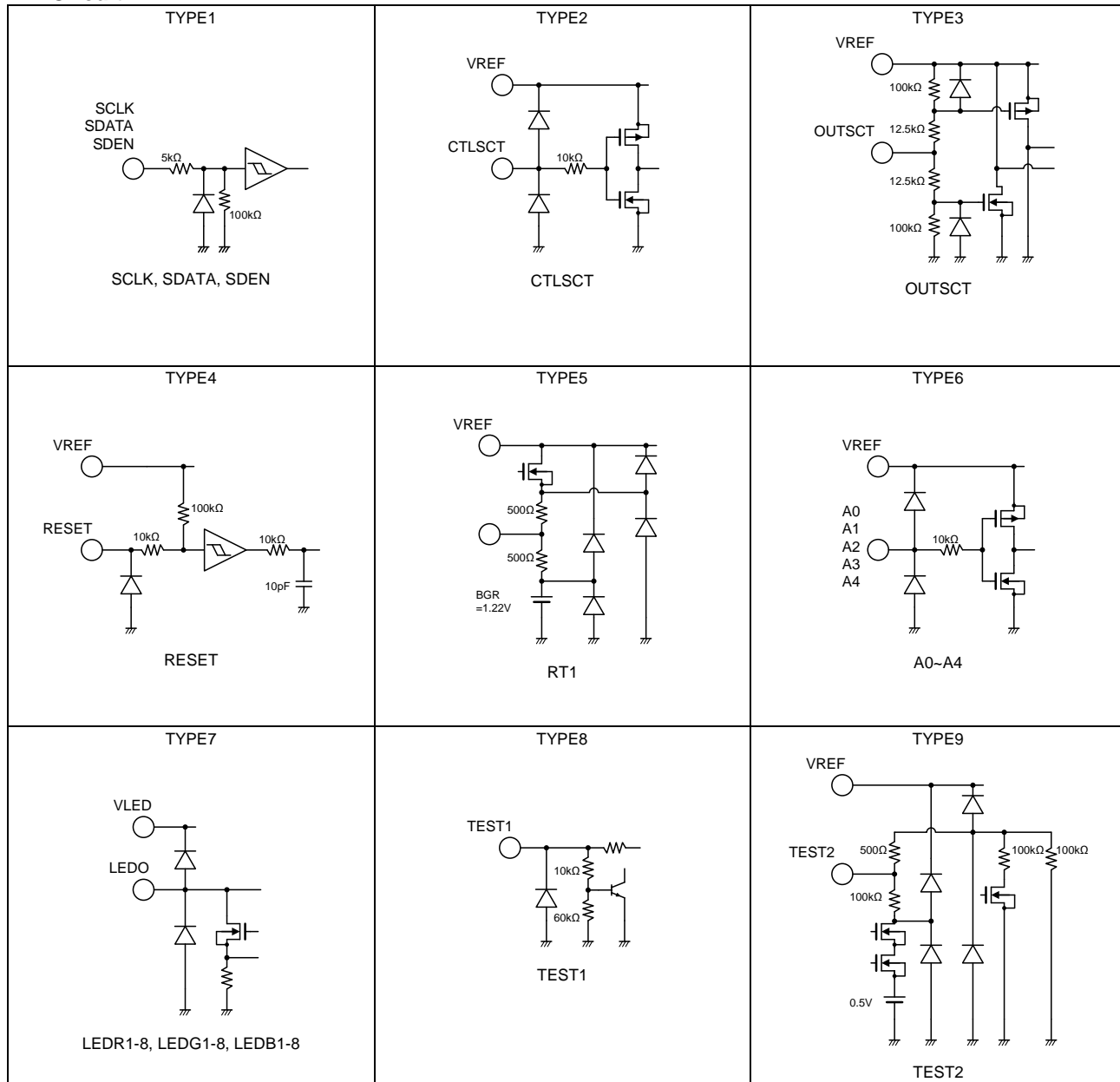
## Pin Descriptions

Pin No.	Pin name	I/O	Description	Pin Circuit
1	VREF	O	Internal supply output pin. Regulates to 5 V if SVCC is higher than 5 V. Bypass with a TBD capacitor.	
2	SCLK	I	Serial interface clock signal input pin. Data is latched at the rising clock edge.	TYPE1
3	SDATA	I	Serial interface input pin. Data frame consists of: Slave_Address[7:0] – Register_Address[7:0] – Data1[7:0] ... DataN[7:0]	TYPE1
4	SDEN	I	Active high, SPI Mode enable signal. Must go low after each SPI frame. Not used for 2 wire interface.	TYPE1
5	CTLSCT	I	Select pin for 2-wire or 3-wire interface. Tie to GND for 3-wire, tie to VREF for 2wire bus.	TYPE2
6	OUTSCT	I	Analog three level selection pin to set current characteristics for the output channels. See "OUTSCT Setting" on page 8 for details.	TYPE3
7	RESET	I	Active high reset input pin. Clears all register settings.	TYPE4
8	RT1	O	Maximum reference current programming pin. Connect a resistor >10 kΩ from this pin to GND to define maximum LED current according to the following formula: $I_{REF} = 1.22 \times 800 / RT$ .	TYPE5
9	NC		No connection.	
10	SGND	-	Analog circuit GND pin.	
11 - 15	A0-4	I	Slave address setting pin. Refer to "Slave address setting" on page 9 for details.	TYPE6
16	LEDR1	I	LED red 1 current input pin.	TYPE7
17	LEDG1	I	LED green 1 current input pin.	TYPE7
18	LEDB1	I	LED blue 1 current input pin.	TYPE7
19	PGND1	-	GND pin dedicated for LED driver. Connect directly to ground plane.	
20	LEDR2	I	LED red 2 current input pin.	TYPE7
21	LEDG2	I	LED green 2 current input pin.	TYPE7
22	LEDB2	I	LED blue 2 current input pin.	TYPE7
23	LEDR3	I	LED red 3 current input pin.	TYPE7
24	LEDG3	I	LED green 3 current input pin.	TYPE7
25	LEDB3	I	LED blue 3 current input pin.	TYPE7
26	PGND2	-	GND pin dedicated for LED driver. Connect directly to ground plane.	
27	LEDR4	I	LED red 4 current input pin.	TYPE7
28	LEDG4	I	LED green 4 current input pin.	TYPE7
29	LEDB4	I	LED blue 4 current input pin	TYPE7
30	VLED		Protection for LED drivers. For higher LED voltages. VLED must be limited to 42.0 V (max).	
31	NC		No connection	
32	LEDR5	I	LED red 5 current input pin.	TYPE7

Continued on next page.

Pin No.	Pin name	I/O	Description	Pin Circuit
33	LEDG5	I	LED green 5 current input pin.	TYPE7
34	LEDB5	I	LED blue 5 current input pin.	TYPE7
35	PGND3	-	GND pin dedicated for LED drivers 4 and 5. Connect directly to ground plane.	
36	LEDR6	I	LED red 6 current input pin.	TYPE7
37	LEDG6	I	LED green 6 current input pin.	TYPE7
38	LEDB6	I	LED blue 6 current input pin.	TYPE7
39	LEDR7	I	LED red 7 current input pin.	TYPE7
40	LEDG7	I	LED green 7 current input pin.	TYPE7
41	LEDB7	I	LED blue 7 current input pin.	TYPE7
42	PGND4	-	GND pin dedicated for LED drivers 6 and 7. Connect directly to ground plane.	
43	LEDR8	I	LED red 8 current input pin.	TYPE7
44	LEDG8	I	LED green 8 current input pin.	TYPE7
45	LEDB8	I	LED blue 8 current input pin.	TYPE7
46	TEST1	I	Test1 pin (connected to GND)	TYPE8
47	TEST2	I	Test2 pin (connected to GND)	TYPE9
48	SVCC	-	System power supply input. For LED supply voltages from 3 to 12 V connect directly to LED supply. For higher LED voltages SVCC must be limited to 13.6 V (max).	

### Pin Circuit



# SPECIFICATIONS

## Absolute Maximum Ratings (Note 1,3)

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	VCC max		13.6	V
	VLED		42	V
	VREF		5.8	V
Output voltage	VO max	LED off	42	V
Output current	IO max	Open drain	100	mA
Allowable power dissipation	Pd max	Ta ≤ 25°C (Note 2)	1.25	W
Operating temperature	Topr		-25 to +85	°C
Operating Junction Temperature	Tj		-25 to +150	°C
Storage temperature	Tstg		-40 to +150	°C

- Stresses exceeding those listed in the Maximum Rating table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
- Specified board: 114.3mm × 76.1mm × 1.6mm, glass epoxy board. Exposed Die-pad area is not a substrate mounting.
- If you should intend to use this IC continuously under high temperature, high current, high voltage, or drastic temperature change, even if it is used within the range of absolute maximum ratings or operating conditions, there is a possibility of decrease reliability. Please contact us for a confirmation.

## Recommended Operating Conditions (Note 4)

Parameter	Symbol	Pin	Ratings	Unit
Operating supply voltage range	VCC op	SVCC	3.0 to 12.8	V
	VLED op	VLED	3.0 to 42	V
	VREF op	VREF	3.0 to 5.5	V

- Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## Electrical Characteristics at Ta = 25°C, 3.3 V < VCC < 5 V (Note 5)

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply current	ICC1	All LEDs off	1.8	2.3	2.9	mA
Reference current pin voltage	VRT	RT1 = 30 kΩ	1.14	1.22	1.30	V
Line regulation	ΔIL	VO = 0.7 to 4.0 V (Same channel line regulation)	-10			%
Output current accuracy	ΔIO L	IO = 32.40 mA (Between bits pairing characteristics)			5	%
LED driver output current 1	IMAX1	RT1 = 30 kΩ LED OUTSCT = L	30.0	32.4	34.8	mA
LED output on resistance 1	Ron1	IO = 10 mA		10	20	Ω
OFF leak current	Ileak	LED OFF			10	μA
VCC Power on RESET voltage	VPOR	POR release voltage threshold		2.5		V
	VRST	Undervoltage lockout threshold		2.3		V
VREF voltage	VREF	VREF = open		4.9		V
VREF voltage	VREF1	VCC = 6.0 V, IO = 10 mA	4.7	5.1	5.4	V

- Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

**Control Circuit at Ta = 25°C, V<sub>CC</sub> = VREF = 5.0 V (Note 5)**

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
H level 1	VH1	Input H level OUTSCT	4.5		5.0	V
M level 1	VM1	Input M level OUTSCT	1.8		3.0	V
L level 1	VL1	Input L level OUTSCT	-0.2		0.5	V
H level 2	VH2	Input H level CTLSCT	3.5		5.0	V
L level 2	VL2	Input L level CTLSCT	-0.2		0.5	V
H level 3	VH3	Input H level RESET	4.0		5.0	V
L level 3	VL3	Input L level RESET	-0.2		1.0	V
H level 4	VH4	Input H level SCLK, SDATA, SDEN	4.0		5.0	V
L level 4	VL4	Input L level SCLK, SDATA, SDEN	-0.2		1.0	V
H level 5	VH5	Input H level A0 to A4	3.5		5.0	V
L level 5	VL5	Input L level A0 to A4	-0.2		0.5	V

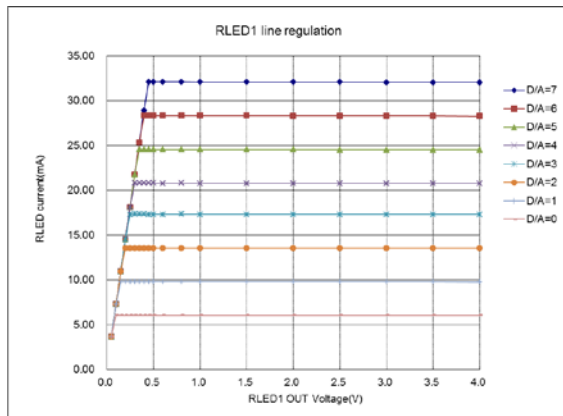
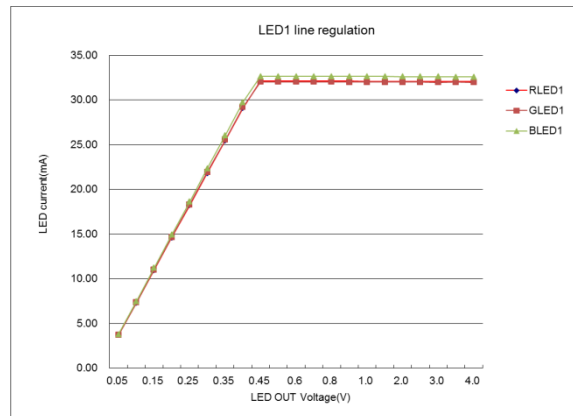
**Control Circuit at Ta = 25°C, V<sub>CC</sub> = VREF = 3.3 V (Note 5)**

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
H level 1	VH1	Input H level OUTSCT	2.8		3.3	V
M level 1	VM1	Input M level OUTSCT	1.2		1.7	V
L level 1	VL1	Input L level OUTSCT	-0.2		0.5	V
H level 2	VH2	Input H level CTLSCT	2.3		3.3	V
L level 2	VL2	Input L level CTLSCT	-0.2		0.5	V
H level 3	VH3	Input H level RESET	2.7		3.3	V
L level 3	VL3	Input L level RESET	-0.2		0.6	V
H level 4	VH4	Input H level SCLK, SDATA, SDEN	2.7		3.3	V
L level 4	VL4	Input L level SCLK, SDATA, SDEN	-0.2		0.6	V
H level 5	VH5	Input H level A0 to A4	2.3		3.3	V
L level 5	VL5	Input L level A0 to A4	-0.2		0.5	V

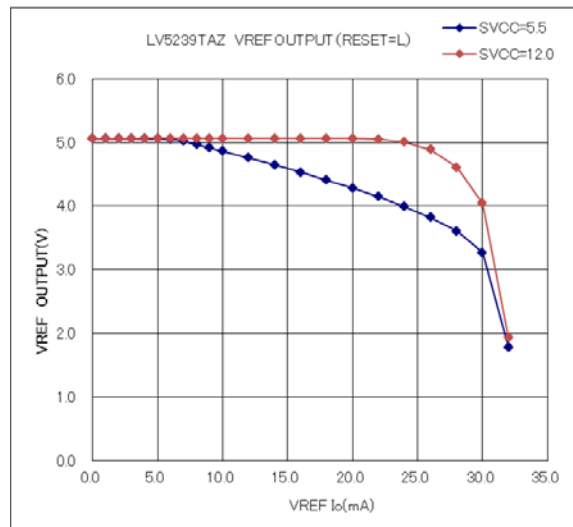
**Serial bus timing conditions**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Cycle time	tcy1	SCLK clock period	200	-	-	ns
Data setup time	ts0	SDEN setup time relative to the rise of SCLK	90	-	-	ns
	ts1	SDATA setup time relative to the rise of SCLK	60	-	-	ns
Data hold time	th0	SDEN hold time relative to the fall of SCLK	200	-	-	ns
	th1	SDATA hold time relative to the fall of SCLK	60	-	-	ns
Pulse width	tw1L	Low period pulse width of SCLK	90	-	-	ns
	tw1H	High period pulse width of SCLK	90	-	-	ns
	tw2L	Low period pulse width of SDEN	1	-	-	µs

LEDOUT Line regulation



VREF OUT Load regulation



# Detailed Functional Description

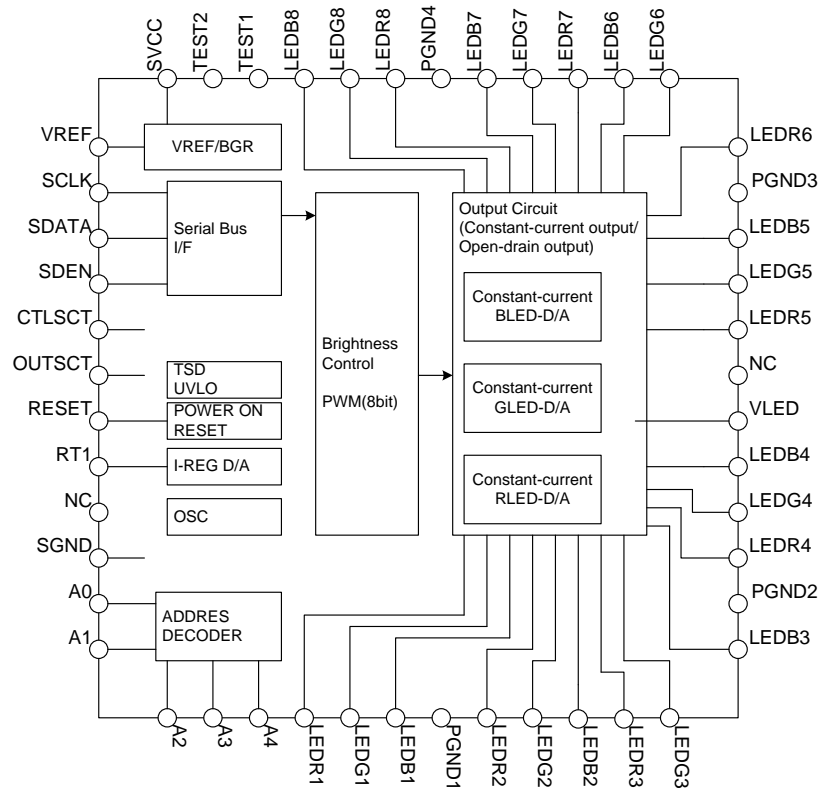


Figure 2: Block Diagram

## System Startup and Shutdown (SVCC, RESET)

The LV5239TA is supplied via SVCC. If the voltage on SVCC rises above the POR level of 2.5 V (typ) the

system setup registers are being reset to their default state, and the reference internal reference circuit at VREF starts up.

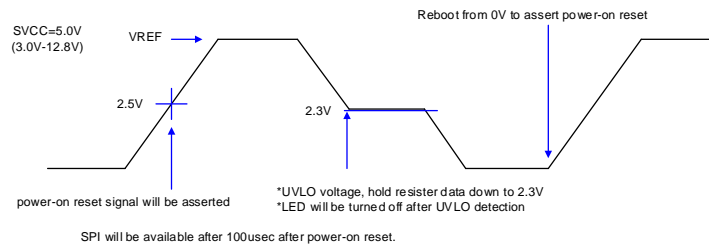


Figure 3: SVCC startup and shutdown

SVCC can be connected to the LED supply of the application as long as that supply is between 3 and 12 V. If the LED supply is higher than 12 V, SVCC must be supplied from a separate source.

An LED reference current is defined by connecting a resistor  $R_{RT}$  between RT1 and GND according to the formula:  $I_{MAX} = 1.22 \times 800 / R_{RT}$ . A fraction of this current (20% - 100%) is applied to each LED channel.

If SVCC drops below the undervoltage lockout level of 2.3 V (typ) the system shuts down.

## Internal References (SVCC, VREF, RT1)

An internal voltage reference of 5 V (typ) is generated at VREF from SVCC. Do not connect external loads.



## LED Driver Configuration (LEDR1-8, LEDG1-8, LEDB1-8, OUTSCT)

The LEDs are connected between the system LED supply and IC channels LEDR1-8, LEDG1-8, LEDB1-8 such that the LED current flows into the IC. Depending on the LED drive voltage, it is possible to connect a single LED or a chain of LEDs.

For details on the relationship between chain length, LED supply voltage and power dissipation see section “Thermal considerations” below.

The LV5239TA can adjust color temperature and brightness for up to 24 LEDs. Color temperature is adjusted by varying the LED current, and brightness (luminance) is adjusted by varying the on-time of the LED a fixed time period (duty-cycle).

### Color temperature control

The 24 LED channels are organized into 3 color groups (Red, Green, Blue) of 8 channels each. The currents for each color group are programmed by a 3 bit register as a

percentage of the LED reference current  $I_{MAX}$ . Percentages of 20, 31, 43, 54, 66, 77 and 100 are possible.

### Luminance control

The brightness of each LED channel is defined by the duty cycle Duty(%): the time  $t_{ON}$  the channel is active during a time window  $t_{CYCLE}$ . The duty cycle is defined by the following formula.  $Duty(\%) = 100 \cdot t_{ON} / t_{CYCLE}$ . Each LED channel has an 8-bit register to vary the duty cycle between OFF (0.0%) and 99.6% in steps of 0.39% each.

The PWM period is defined by the 3 most significant bits at address 00h starting with 0.5msec, doubling with each bit up to 8ms.

### OUTSCT Settings

In addition to the settings mentioned above, it is also possible to subdivide the 8 LED channels within the color groups into 6 and 2 LED channels grouped in the following way:

OUTSCT Level	LED Driver Output Pin	
	LED1, LED2, LED3, LED4, LED5, LED6	LED7, LED8
L=-0.2 to 0.3V	Constant current output Set maximum current by built-in D/A (3 bits) 6.40 mA to 32.40 mA, RT1 = 30 kΩ (f = 1 MHz)	Same as the other LEDs
H=4.7 to 5.0V	Open drain output Set current by external resistor. $R_{ON} = 10 \Omega$	Same as the other LEDs
M=1.8 to 3.0V	Constant current output Set maximum current by built-in D/A (3 bits) 6.40 mA to 32.40 mA, RT1 = 30 kΩ (f = 1 MHz)	Open drain output Set current by external resistor. $R_{ON} = 10 \Omega$

## Thermal Considerations

Supplying a large number of LEDs from the LV5239TA leads to a rise in chip temperature. The self-heating depends on:

- the drive current  $I_O$  flowing into the LED channel
- the voltage at the output  $V_{OUT}$  of the LED channel
- and the duty cycle  $D$  they are driven with

leading to the following formula for dissipated power in each channel:

$$P_{CH} = I_O \times V_{OUT} \times D$$

The only architecture sensitive value is  $V_{OUT}$ . It must be greater than 0.5 V (min) to allow for regulation, but also as small as possible. It is therefore advisable to connect the maximum possible number of LEDs in series to one channel.

The total power dissipation  $P_{TOT}$  of the IC is then the sum of all  $P_{CH}$  together.  $P_{TOT}$  must not exceed the power allowed by the safe operating area shown in Figure 4.

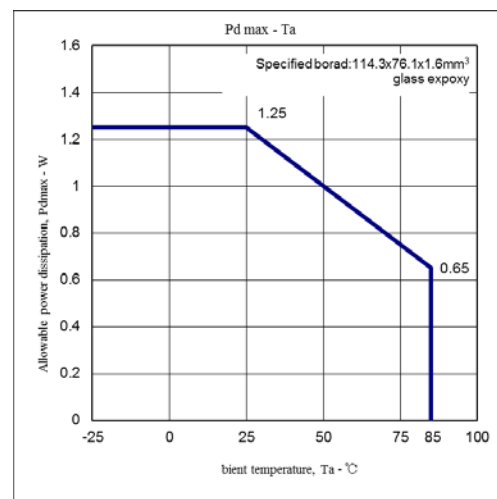


Figure 4: Safe Operating Area

To make evaluation of the actual drive capability easier, a number of plots are included after page 13. These plots show the safe operating area for LED string current  $I_O$  on the vertical axis, the number of active RGB Channels on the horizontal axis (times 3 for each color group) along with individual duty cycle curves at a given  $V_{OUT}$  and temperature.

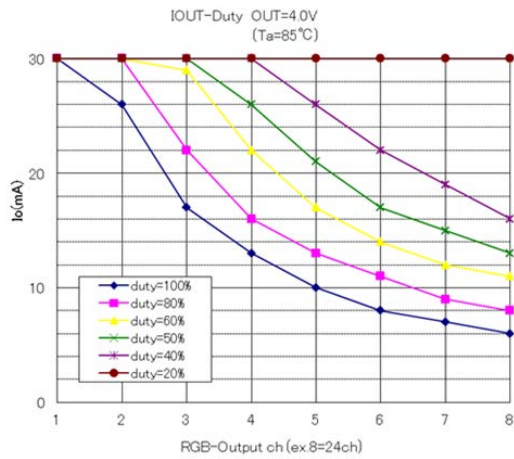


Figure 5: Thermally Safe Operation Example

The example in Figure 5 shows operation of up to 8 RGB channels (24LEDs) at 85°C and a channel voltage of 4 V. Operation below the curve is safe! It is therefore possible to drive 2 RGB LEDs (6 channels) at 20 mA or 8 RGB LEDs (24 channels) at 4 mA with 100% duty cycle. If only 20% duty cycle is required, all 8 RGBLEDs can be driven with 20 mA.

See more examples in section “LEDOUT Duty Cycle De-rating” starting on page 13.

### Overtemperature shutoff

To protect the circuit from permanent damage or fire, overtemperature shutoff is implemented. If the junction temperature of the IC reaches 175°C, all LED outputs are turned OFF. The thermal shut down is not latched, so when the temperature falls below 130°C activity resumes.

### Serial Bus Communication (SCLK, SDATA, SDEN, CTLST)

All parameters described above are written to the LV5239TA via a single directional 2-wire or 3-wire serial bus with a clock frequency of up to 5 MHz. The bus type is defined by the state of pin CTLST (VREF = 2-wire, GND = 3-wire).

Each bus message consists of an 8bit slave (IC) address, followed by an 8bit register address, followed by one or more 8bit data words. The register address will self-increment for consecutive data words as long as the communication is valid. After the last address was written, the next data word will be written to address 00h again. For detailed information on addresses and register contents see section “Register Map” on page 12.

### Slave Address (A4-A0)

Each IC is identified by its unique slave address. The most significant two bits of the 8bit slave (IC) address are fixed to 10b. 32 Slave addresses are hardware defined by pins A0-A4 as described below.

	SA7	SA6	SA5	SA4	SA3	SA2	SA1	SA0
ADDRESS	1	0	A4	A3	A2	A1	A0	0

Terminal PIN (Input)					SLAVE ADDRESS							
A4	A3	A2	A1	A0	SA7	SA6	SA5	SA4	SA3	SA2	SA1	SA0
L	L	L	L	L	1	0	0	0	0	0	0	0
...					1	0	A4	A3	A2	A1	A0	0
H	H	H	H	H	1	0	1	1	1	1	1	0

### 3-wire Serial Bus Communication (SCLK, SDATA, and SDEN)

In 3-wire communication a frame is started with a rising edge of SDEN and terminated with a falling edge of

SDEN. SCLK latches data at the rising edge. The smallest data word is 24bits long consisting of:

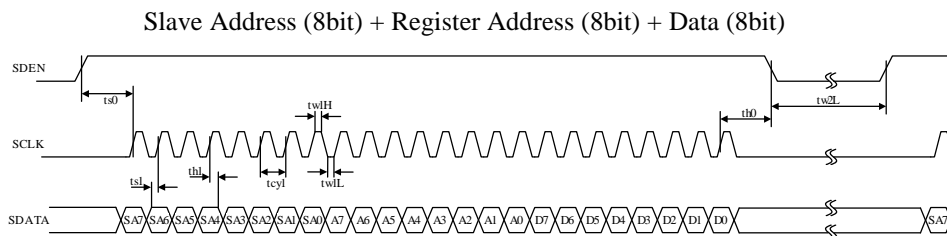
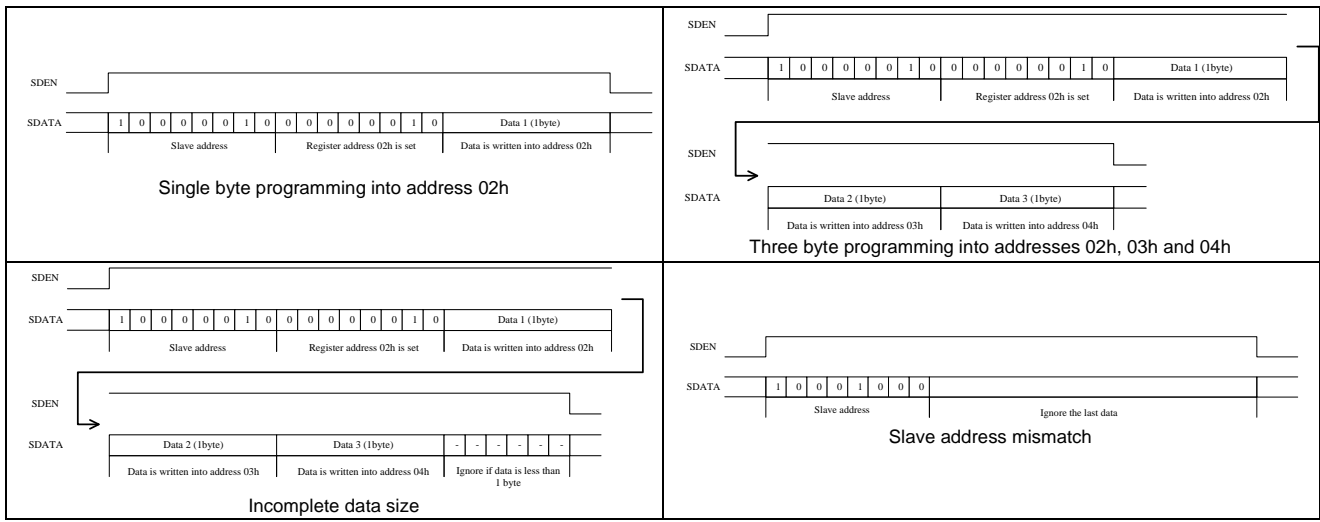


Figure 6: 3 Wire Serial Data Frame

If the number of SCLK transitions is less than 23, Data is not latched. If it is 25 or more, the register address is automatically incremented and the next data word will be latched after eight clock cycles.



**2-wire Serial Bus Communication (SCLK, SDATA)**

In 2-wire communication the LV5239TA watches SDATA at every rising SCLK edge. A data frame begins after START condition: nine consecutive detections of a “1” (high) followed by a “0” (BLANK). This is true even during an ongoing data transfer: serial communication will be restarted by a START condition (“11111111”) + BLANK (“0”).

After start detection, the eight bit slave address will be latched after receiving a BLANK (0h) with the ninth bit. The register address will be latched after receiving a BLANK”0” after eight address bits. The third byte is the

data byte which was addressed by the register address received before. The data byte will be latched after receiving a BLANK”0” in position nine after eight data bits.

When data bytes continue after this, the register address will be automatically incremented after each byte transfer is completed after receiving BLANK”0”.

If the BLANK after a data transfer is “1”, including slave address and register address, the single byte data just before it will not be written, and subsequent data is ignored until another START condition is detected.

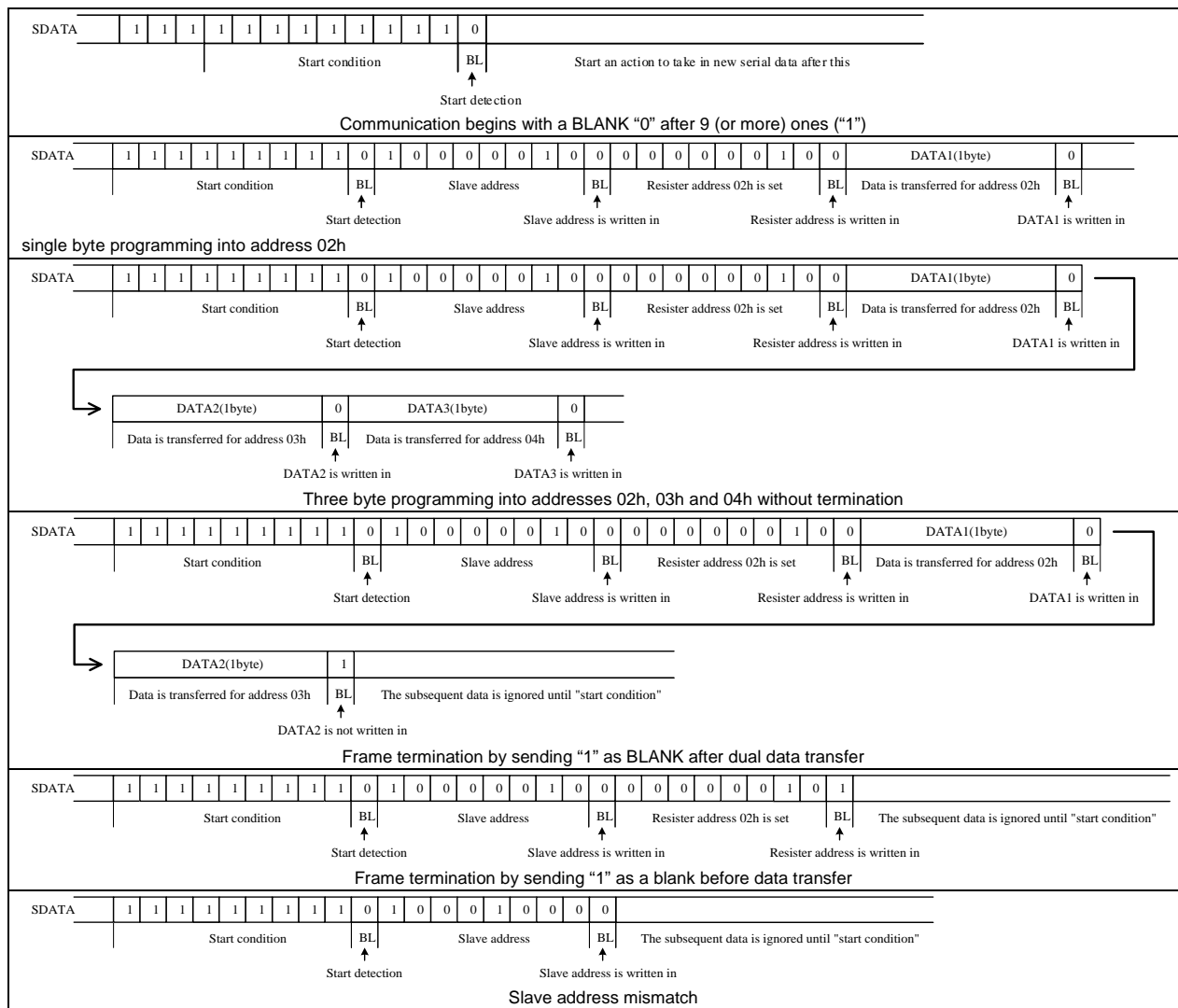
bit	ST8	ST7	ST6	ST5	ST4	ST3	ST2	ST1	ST0	BL	SA7	SA6	SA5	SA4	SA3	SA2	SA1	SA0	BL	A7	A6	A5	A4	A3	A2	A1	A0	BL	D7	D6	D5	D4	D3	D2	D1	D0	BL
SDATA	1	1	1	1	1	1	1	1	1	0	1	0						0	0								0									0	
Parameter	Start condition									BLANK	Slave address								BLANK	Register address								BLANK	Data								BLANK

▲ Fix slave address
▲ Fix register address
▲ Fix Data

Figure 7 : 2-wire Serial Communication Frame

Minimum Data length is 37bits:  
 Start condition “11111111”(9bit) + BLANK(“0”)  
 + Slave address(8bit) + BLANK(“0”) + Register address(8bit) + BLANK(“0”) + Data(8bit) + BLANK(“0”).

Note: When SCLK is less than 27th clocks and/or BLANK is “1” instead of “0” after start detection, will not take in SDATA. When SCLK is higher than 28th clock track, start detection is confirmed, register address is incremented every 1byte (8bit) + BLANK (“0”).



## Register Map

After POR all registers are cleared.

### Frequency and Color Temperature Registers

Addr.	Register	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]	Description
00h	LEDR&PWM	F_PWM[2:0]				I_LEDR[2:0]				LEDR current setting (LEDR1 ~ LED8)
							0	0	0	20% of I <sub>max</sub> (6.4 mA @ RT = 30 k)
							0	0	1	31% of I <sub>max</sub> (10.15 mA @ RT = 30 k)
							0	1	0	43% of I <sub>max</sub> (13.90 mA @ RT = 30 k)
							0	1	1	54% of I <sub>max</sub> (17.65 mA @ RT = 30 k)
							1	0	0	66% of I <sub>max</sub> (21.15 mA @ RT = 30 k)
							1	0	1	77% of I <sub>max</sub> (24.90 mA @ RT = 30 k)
							1	1	0	88% of I <sub>max</sub> (28.65 mA @ RT = 30 k)
							1	1	1	I <sub>max</sub> = 1.22 x 800 / RT (32.4 mA @ RT = 30 k)
		0	0	0						0.5 ms (PWM-Duty cycle time)
		0	0	1						1.0 ms (PWM-Duty cycle time)
		0	1	0						2.0 ms (PWM-Duty cycle time)
		0	1	1						4.0 ms (PWM-Duty cycle time)
1	0	0						8.0 ms (PWM-Duty cycle time)		
01h	LEDG Current					I_LEDG[2:0]				LEDG current setting (LEDG1~LEDG8)
							0	0	0	20% of I <sub>max</sub> (6.4 mA @ RT = 30 k)
							0	0	1	31% of I <sub>max</sub> (10.15 mA @ RT = 30 k)
							0	1	0	43% of I <sub>max</sub> (13.90 mA @ RT = 30 k)
							0	1	1	54% of I <sub>max</sub> (17.65 mA @ RT = 30 k)
							1	0	0	66% of I <sub>max</sub> (21.15 mA @ RT = 30 k)
							1	0	1	77% of I <sub>max</sub> (24.90 mA @ RT = 30 k)
							1	1	0	88% of I <sub>max</sub> (28.65 mA @ RT = 30 k)
					1	1	1	I <sub>max</sub> = 1.22 x 800 / RT (32.4 mA @ RT = 30 k)		
02h	LEDB Current					I_LEDB[2:0]				LEDB current setting (LEDB1~8)
							0	0	0	20% of I <sub>max</sub> (6.4 mA @ RT = 30 k)
							0	0	1	31% of I <sub>max</sub> (10.15 mA @ RT = 30 k)
							0	1	0	43% of I <sub>max</sub> (13.90 mA @ RT = 30 k)
							0	1	1	54% of I <sub>max</sub> (17.65 mA @ RT = 30 k)
							1	0	0	66% of I <sub>max</sub> (21.15 mA @ RT = 30 k)
							1	0	1	77% of I <sub>max</sub> (24.90 mA @ RT = 30 k)
							1	1	0	88% of I <sub>max</sub> (28.65 mA @ RT = 30 k)
							1	1	1	I <sub>max</sub> = 1.22x800/RT (32.4 mA @ RT = 30 k)

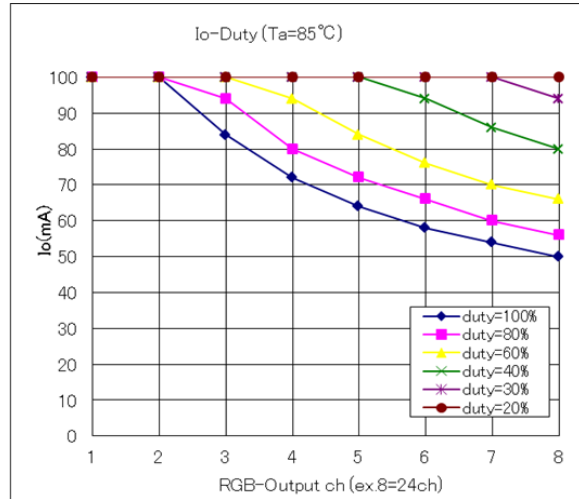
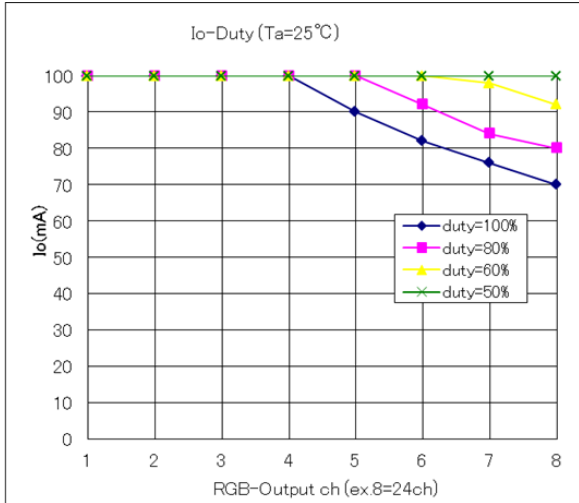
### Luminance Registers

Addr.	Register	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]	Description
03h	PWM SEL LEDR	R8	R7	R6	R5	R4	R3	R2	R1	Select PWM or Full on for LEDR1 ~ LEDR8
										0 = Use PWM as set by the registers below. 1 = Full on (100%PWM)
04h	PWM SEL LEDG	G8	G7	G6	G5	G4	G3	G2	G1	Select PWM or Full on for LEDG1 ~ LEDG8
										0 = Use PWM as set by the registers below. 1 = Full on (100%PWM)
05h	PWM SEL LEDB	B8	B7	B6	B5	B4	B3	B2	B1	Select PWM or Full on for LEDB1 ~ LEDB8
										0 = Use PWM as set by the registers below. 1 = Full on (100%PWM)
06h	LEDR1 Duty	R1[7]	R1[6]	R1[5]	R1[4]	R1[3]	R1[2]	R1[1]	R1[0]	PWM duty setting for LEDR1
		0	0	0	0	0	0	0	0	Duty(%) = 0.0%
		R1[7:0]								Duty(%) = R1[7:0] / 256
		1	1	1	1	1	1	1	1	Duty(%) = 99.6%
07h	LEDG1 Duty					G1[7:0]				Same as LEDR1 description
08h	LEDB1 Duty					B1[7:0]				
09h	LEDR2 Duty					R2[7:0]				
0Ah	LEDG2 Duty					G2[7:0]				
0Bh	LEDB2 Duty					B2[7:0]				
0Ch	LEDR3 Duty					R3[7:0]				
0Dh	LEDG3 Duty					G3[7:0]				
0Eh	LEDB3 Duty					B3[7:0]				
0Fh	LEDR4 Duty					R4[7:0]				
10h	LEDG4 Duty					G4[7:0]				
11h	LEDB4 Duty					B4[7:0]				
12h	LEDR5 Duty					R5[7:0]				
13h	LEDG5 Duty					G5[7:0]				
14h	LEDB5 Duty					B5[7:0]				
15h	LEDR6 Duty					R6[7:0]				
16h	LEDG6 Duty					G6[7:0]				
17h	LEDB6 Duty					B6[7:0]				
18h	LEDR7 Duty					R7[7:0]				
19h	LEDG7 Duty					G7[7:0]				
1Ah	LEDB7 Duty					B7[7:0]				
1Bh	LEDR8 Duty					R8[7:0]				
1Ch	LEDG8 Duty					G8[7:0]				
1Dh	LEDB8 Duty					B8[7:0]				

# LEDOUT Duty Cycle De-rating

All channels in switch mode(OUTSCT=H)

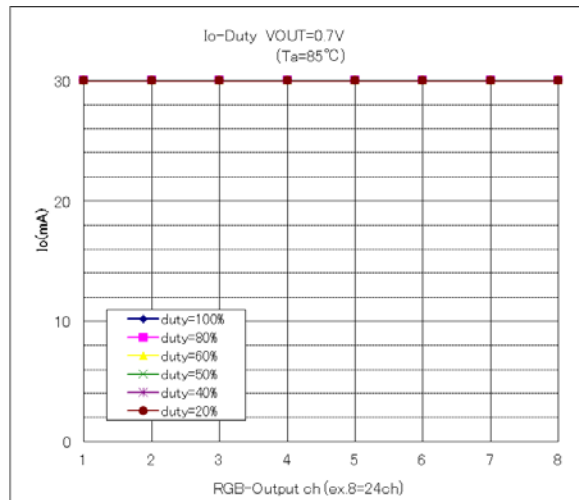
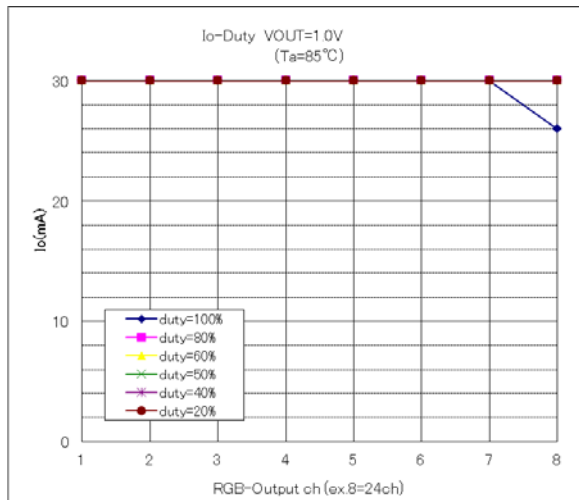
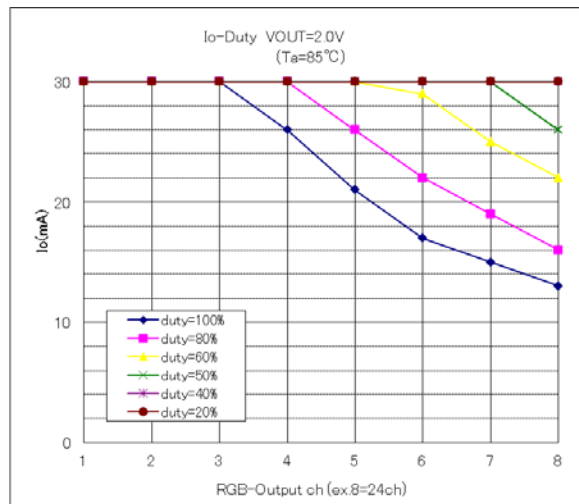
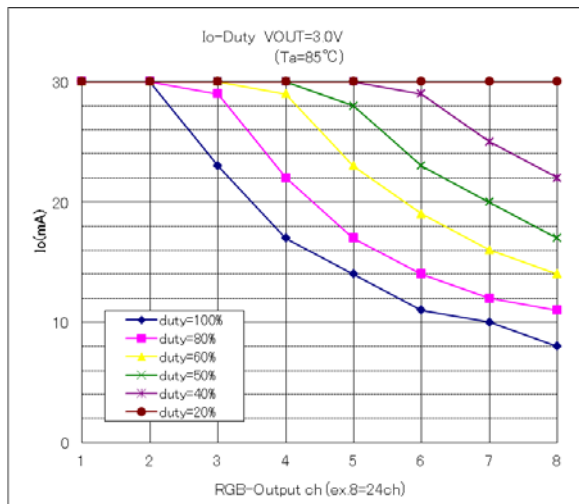
Note: In this case the LED current must be limited by external resistors!



All channels use internal current control (OUTSCT=L)

Note: In this case the LED current must be limited by resistance of RT1. Furthermore, must manage it in

register 00h and 01h and 02h. and manage even the Duty setting.



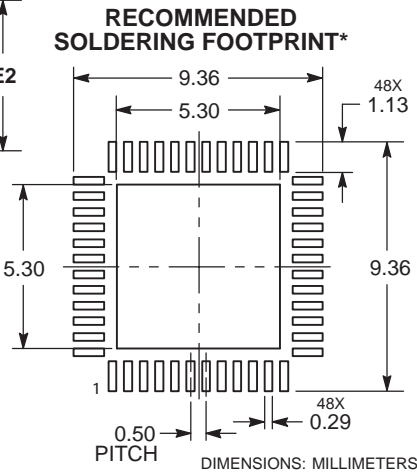
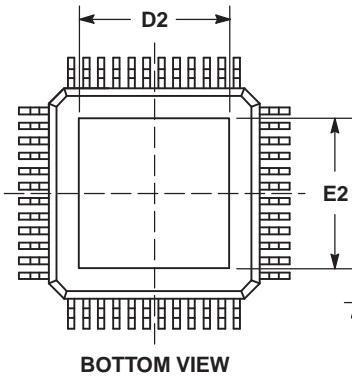
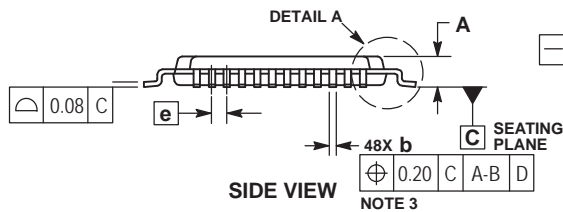
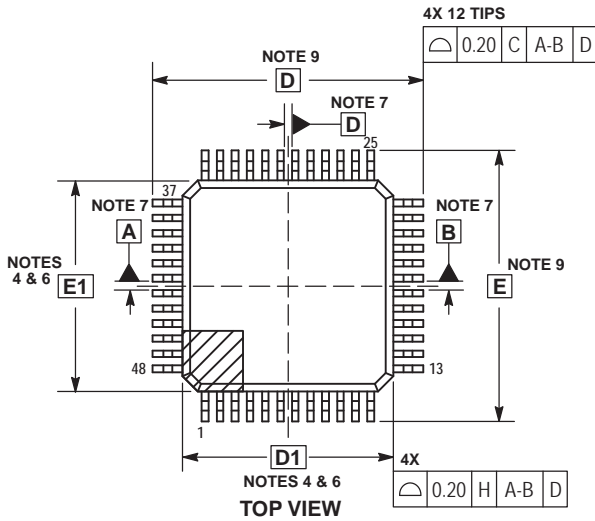
# Package Dimensions

unit : mm

## TQFP48 EP 7x7, 0.5P

CASE 932F

ISSUE C



### NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADII OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY AS MUCH AS 0.15.
6. DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.

DIM	MILLIMETERS	
	MIN	MAX
A	0.95	1.25
A1	0.05	0.15
A2	0.90	1.20
b	0.17	0.27
D	9.00 BSC	
D1	7.00 BSC	
D2	4.90	5.10
E	9.00 BSC	
E1	7.00 BSC	
E2	4.90	5.10
e	0.50 BSC	
L	0.45	0.75
L2	0.25 BSC	
M	0°	7°

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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